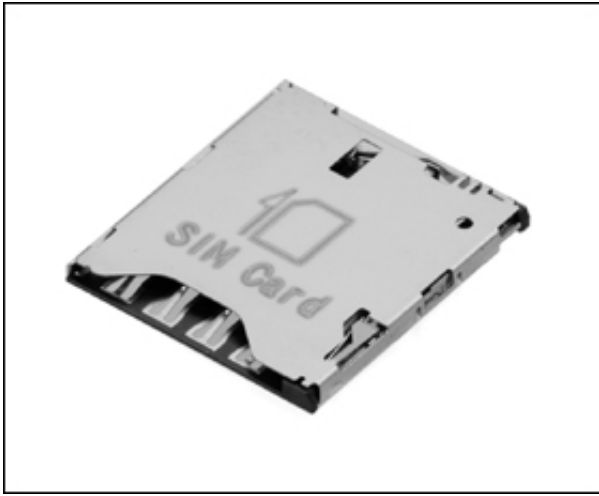

For microSIM Card (Push-push Type) SCGD Series

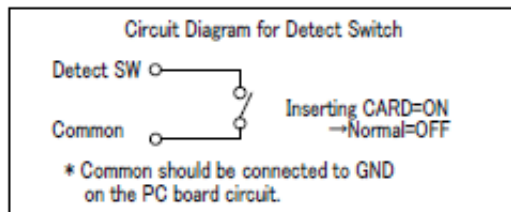
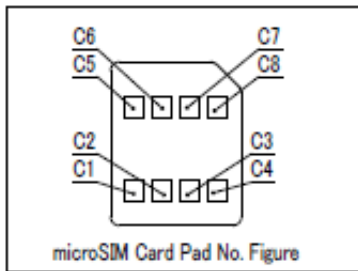
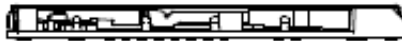
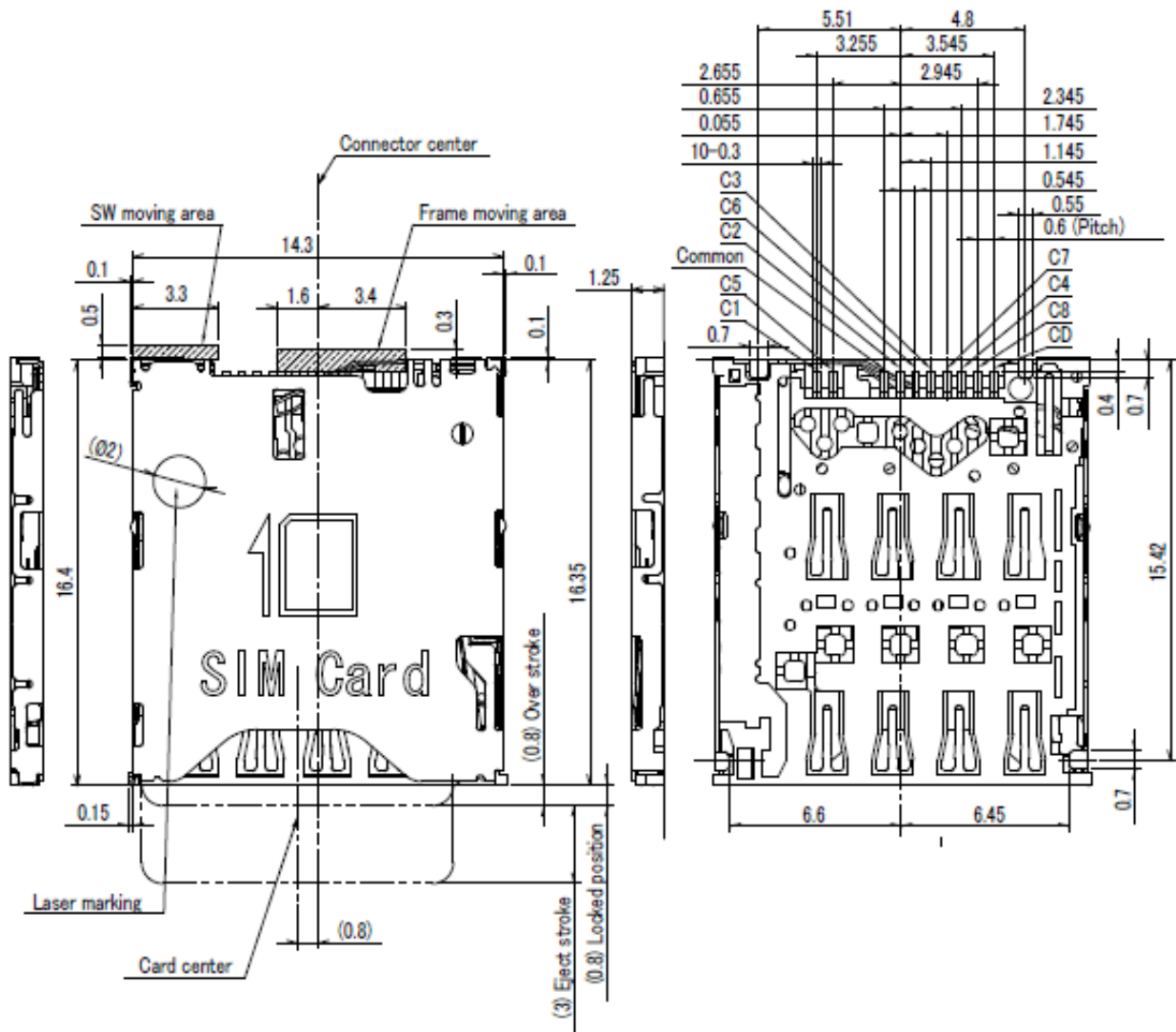
Part number	SCGD1B0309	
Applicable media	microSIM card	
Media ejection structure	Push-push type	
Mounting type	Surface mounting type	
Mounting style	Standard mount	
Card eject stroke	3mm	
Stand-off	0mm	
Minimum order unit (pcs.)	1,600	
Operating temperature range	-25°C to +60°C	
Voltage proof	250V AC 1 minute	
Insulation resistance (Initial)	1,000MΩ min.	
Contact resistance (Initial)	Connector contacts	100mΩ max.
	Detection Switch	500mΩ max.
Insertion and removal cycle	5,000 cycles	

Photo

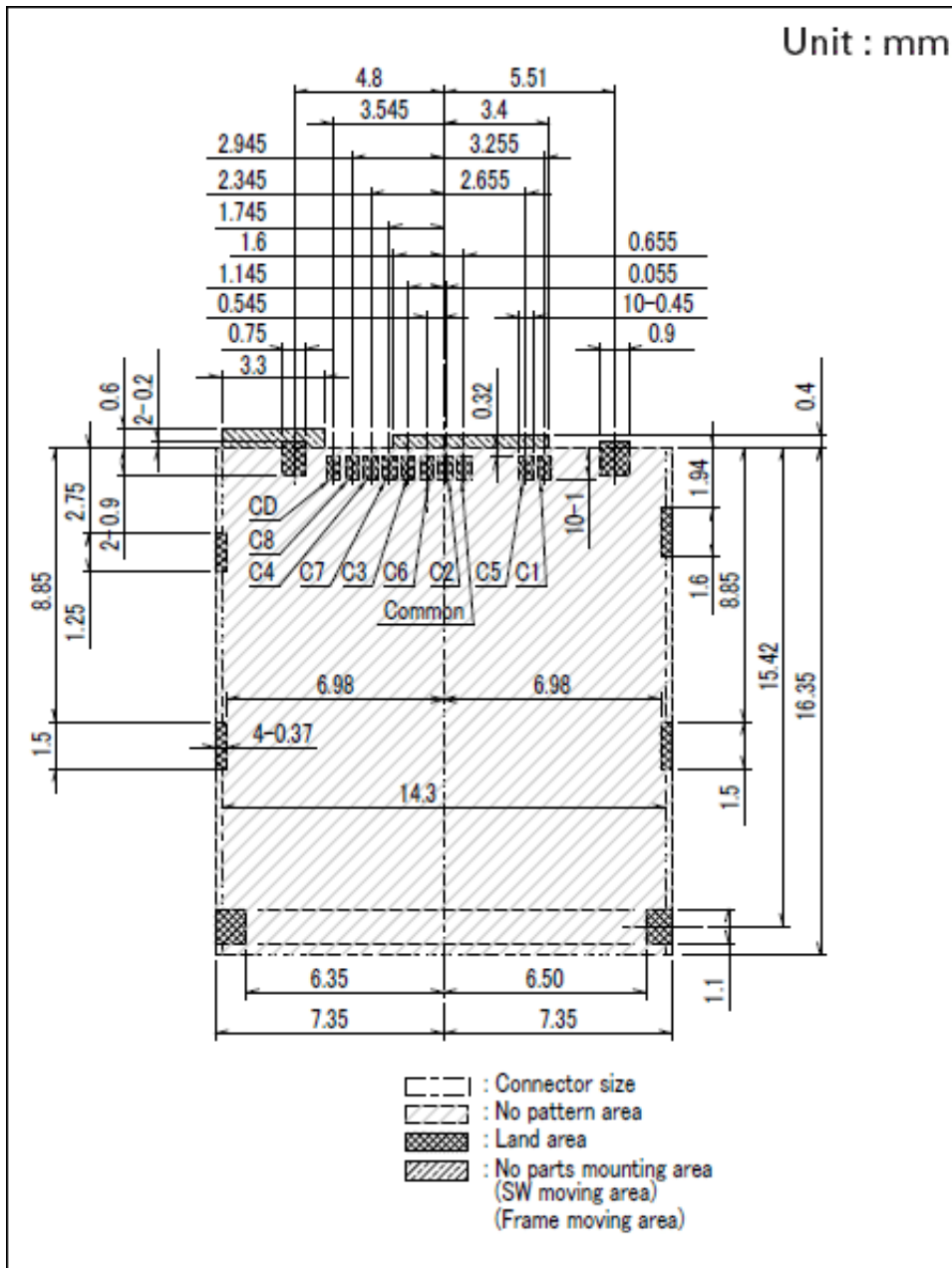


Dimensions

Unit : mm

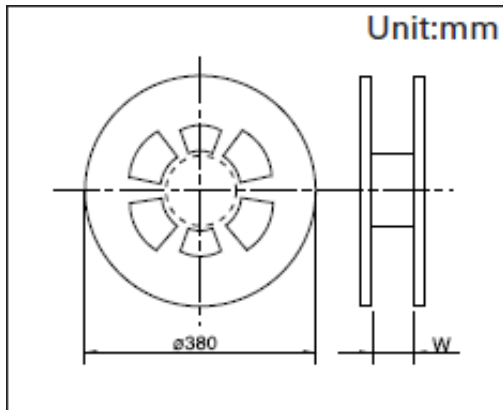


Mounting Dimensions



Packing Specifications

Taping



(pcs.)

1 case / Japan 4,800

1 case / export
packing 9,600

Reel width W(mm) 57.5

Tape width (mm) 56

Export package measurements (mm) 403×403×303

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

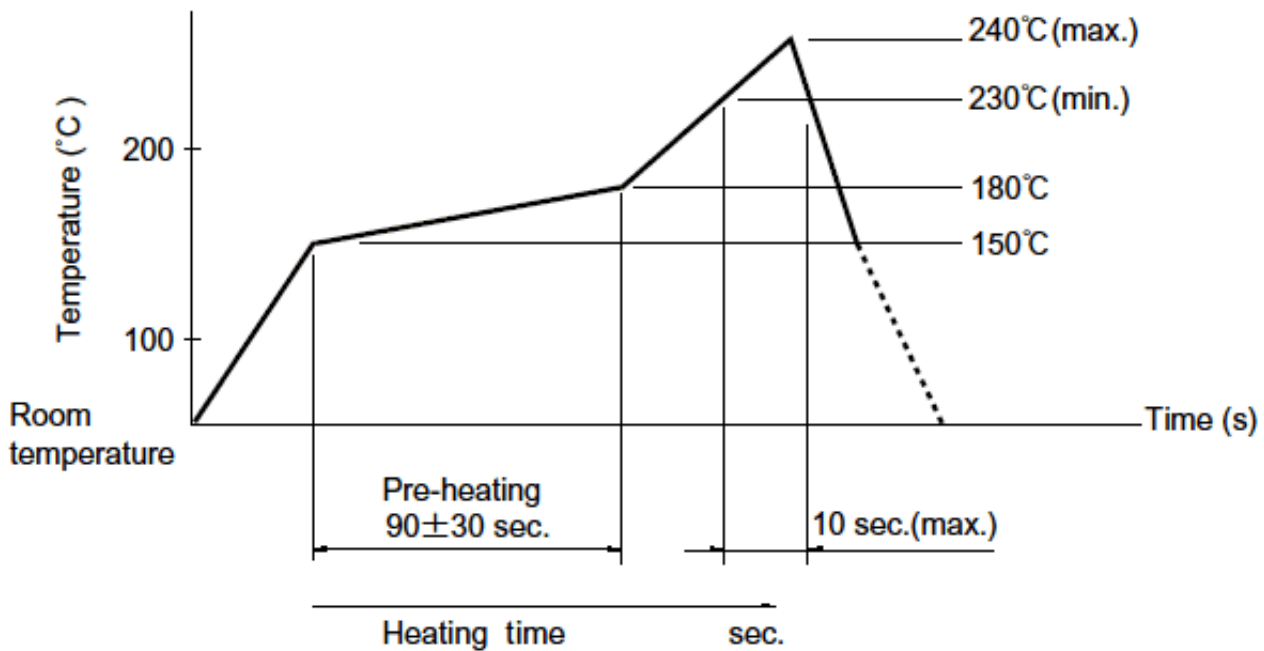
1. Heating method

Double heating method with infrared heater.

2. Temperature measurement

Thermocouple 0.1 to 0.2 Φ CA (K) or CC (T) at soldering portion.

3. Temperature profile.



Notes are common to this series/models.

1. This site catalog shows only outline specifications. When using the products, please obtain formal specifications for supply.
2. Please place purchase orders per minimum order unit (integer).